



GL20N04A4

GL Silicon N-Channel Power MOSFET

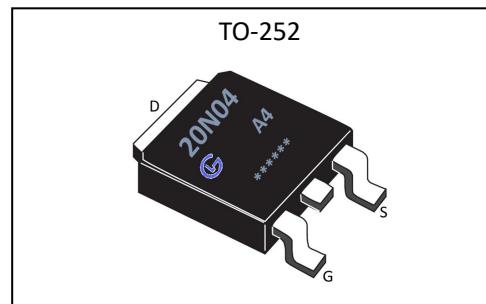
General Description:

The GL20N04A4 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is TO-252, which accords with the RoHS standard.

V_{DSS}	40	V
I_D	20	A
P_D	32.5	W
$R_{DS(ON)MAX}$	25	$m\Omega$

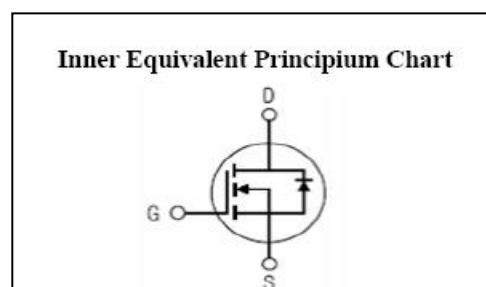
Features:

- $R_{DS(ON)} < 25m\Omega$ @ $V_{GS}=10V$
- High density cell design for ultra low $R_{ds(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation



Applications:

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Absolute (Tc= 25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	40	V
I_D	Continuous Drain Current	20	A
I_{DM}	Pulsed Drain Current	80	A
V_{GS}	Gate-to-Source Voltage	± 20	V
P_D	Power Dissipation	32.5	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	°C



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Electrical Characteristics (T_c= 25°C unless otherwise specified):

OFF Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =40V, V _{GS} =0V, T _a =25°C	--	--	1.0	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+20V	--	--	0.1	μA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-20V	--	--	-0.1	μA

ON Characteristics^{a3}

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DS(ON)}	Drain-to-Source On-Resistance	V _{GS} =10V, I _D =10A	--	--	25	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	--	2.5	V

Pulse width t_p≤380μs, δ≤2%

Dynamic Characteristics^{a4}

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g _{fs}	Forward Transconductance	V _{DS} =15V, I _D =2A	--	3	--	S
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V	--	247	--	pF
C _{oss}	Output Capacitance	f=1.0MHz	--	34	--	
C _{rss}	Reverse Transfer Capacitance		--	19.5	--	

Resistive Switching Characteristics^{a4}

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =20V, I _D =3A	--	6	--	ns
t _r	Rise Time		--	15	--	
t _{d(OFF)}	Turn-Off Delay Time		--	15	--	
t _f	Fall Time		--	10	--	
Q _g	Total Gate Charge	V _{DD} =20V, I _D =3A	--	6	--	nC
Q _{gs}	Gate to Source Charge		--	1	--	
Q _{gd}	Gate to Drain ("Miller")Charge		--	1.3	--	



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Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current ^{a2} (Body Diode)		--	--	20	A
V _{SD}	Diode Forward Voltage ^{a3}	I _S =20A, V _{GS} =0V	--	--	1.5	V

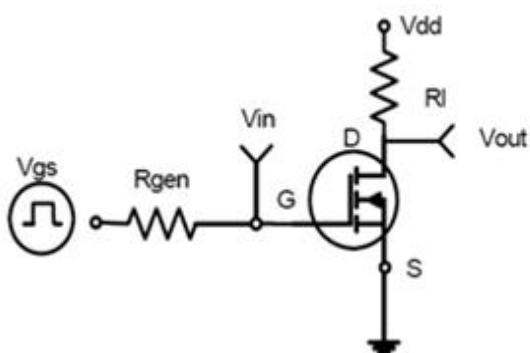
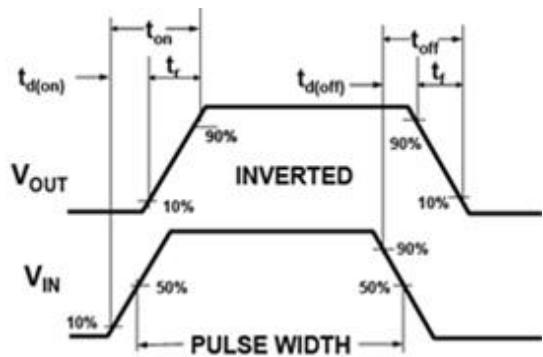
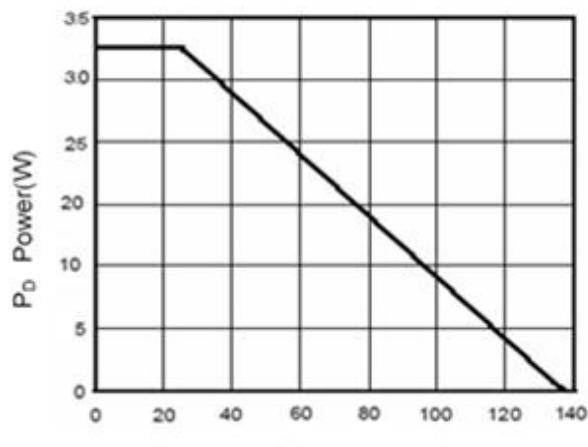
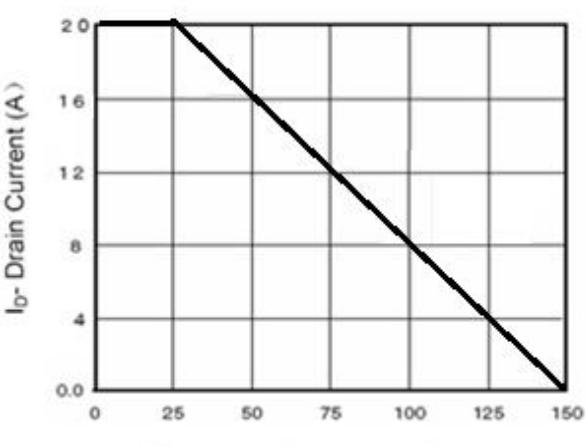
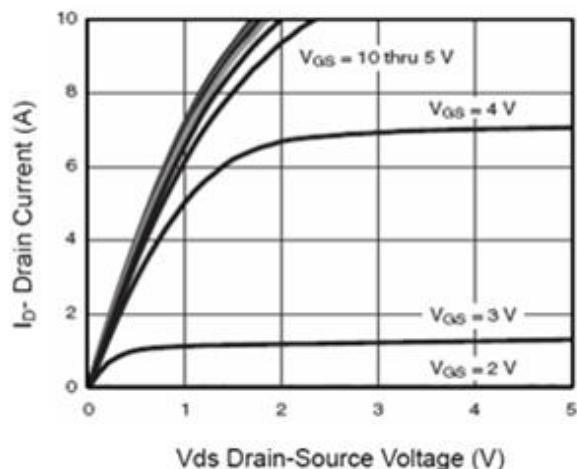
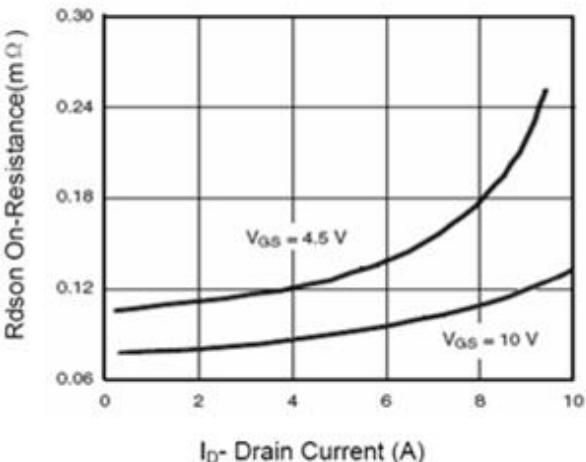
Symbol	Parameter	Typ.	Units
R _{θJC}	Junction-to-Case ^{a2}	3.846	°C/W

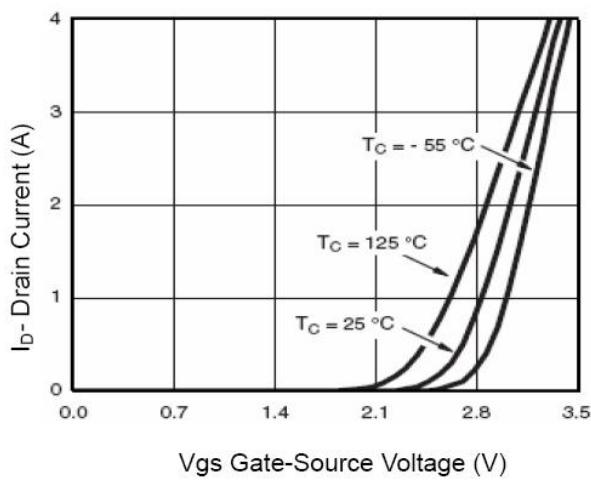
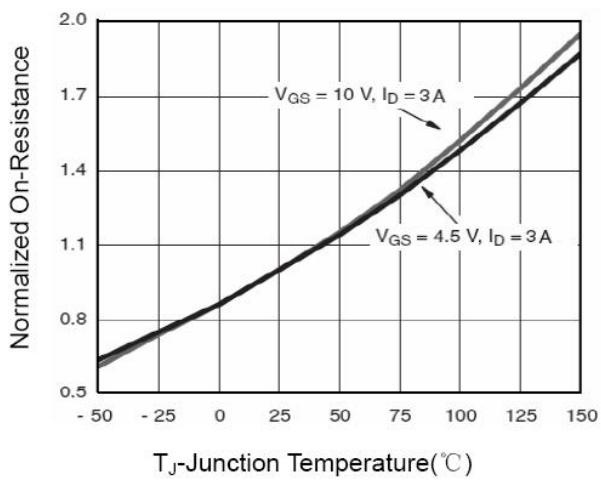
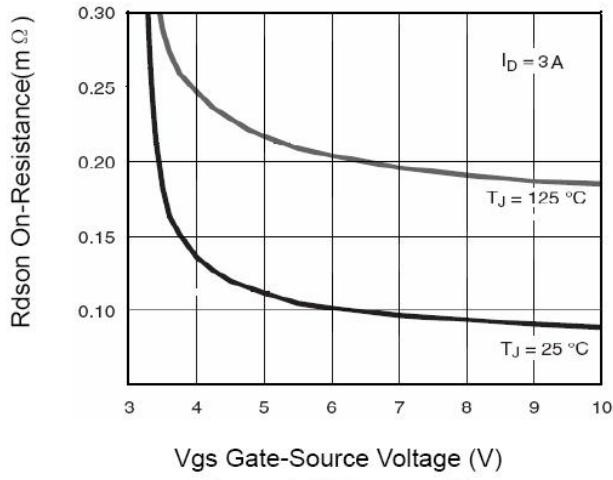
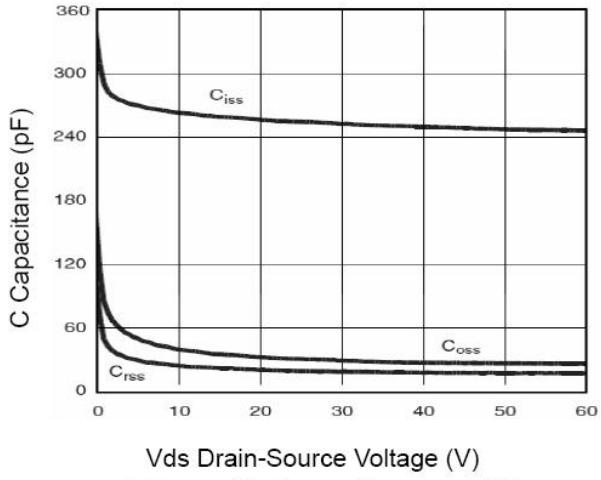
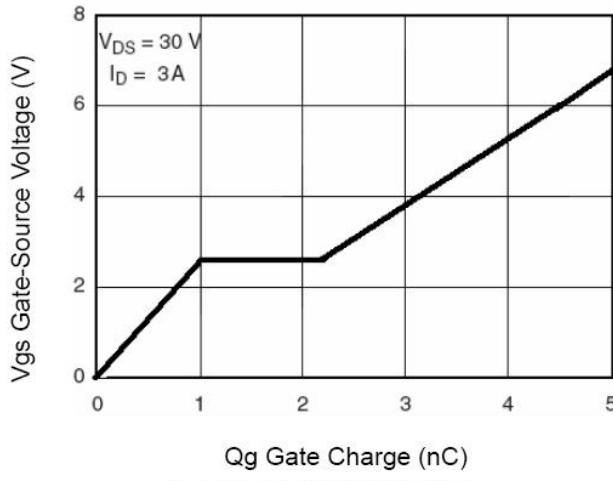
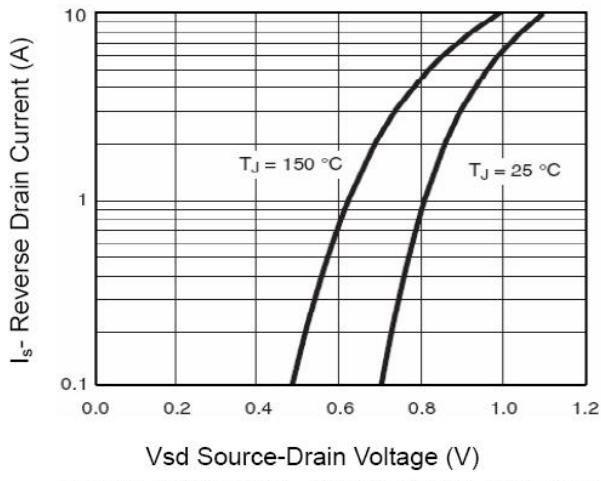
^{a1}: Repetitive Rating: Pulse width limited by maximum junction temperature.

^{a2}: Surface Mounted on FR4 Board, t≤10sec.

^{a3}: Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.

^{a4}: Guaranteed by design, not subject to production

Characteristics Curve:

Figure 1:Switching Test Circuit

Figure 2:Switching Waveforms

Figure 3 Power Dissipation

Figure 4 Drain Current

Figure 5 Output Characteristics

Figure 6 Drain-Source On-Resistance

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Figure 7 Transfer Characteristics

Figure 8 Drain-Source On-Resistance

Figure 9 $R_{DS(on)}$ vs V_{GS}

Figure 10 Capacitance vs V_{DS}

Figure 11 Gate Charge

Figure 12 Source-Drain Diode Forward